# 6 Literatures

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## 6.2 Own publications

### A. Journals


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### B. Conference papers and posters


1. Cai, D., Neyer, A., „Realization of Electrical-Optical-Circuit-Board self-packaging," Proceedings on 57th Electronic Components and Technology Conference, ECTC 2007, Reno, Nevada, USA, 2007, pp. 1368-1374.
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